

ENDCAP GROUNDING AND SHIELDING

Structures shown are primarily aluminum

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Ned Spencer, UCSC,
October 1, 2001

OUTER SUPPORT TUBE THERMAL SPREADER: 150 μm

OUTER SUPPORT TUBE SKIN:
Aluminum Skin on outside face of Support Tube,
75 μm thick, isolated from tube

PP1 with power tape Commoning
DGND has AC tie to Shield

Disks isolated from
support tube CFRP, Tied
to Outer Support Tube Skin

Power tapes have bypass capacitors at PP0,
DGND shorted to Outer Support Tube Skin

Tray is detailed Page 2

Power tapes need no shielding wrap
in service channel

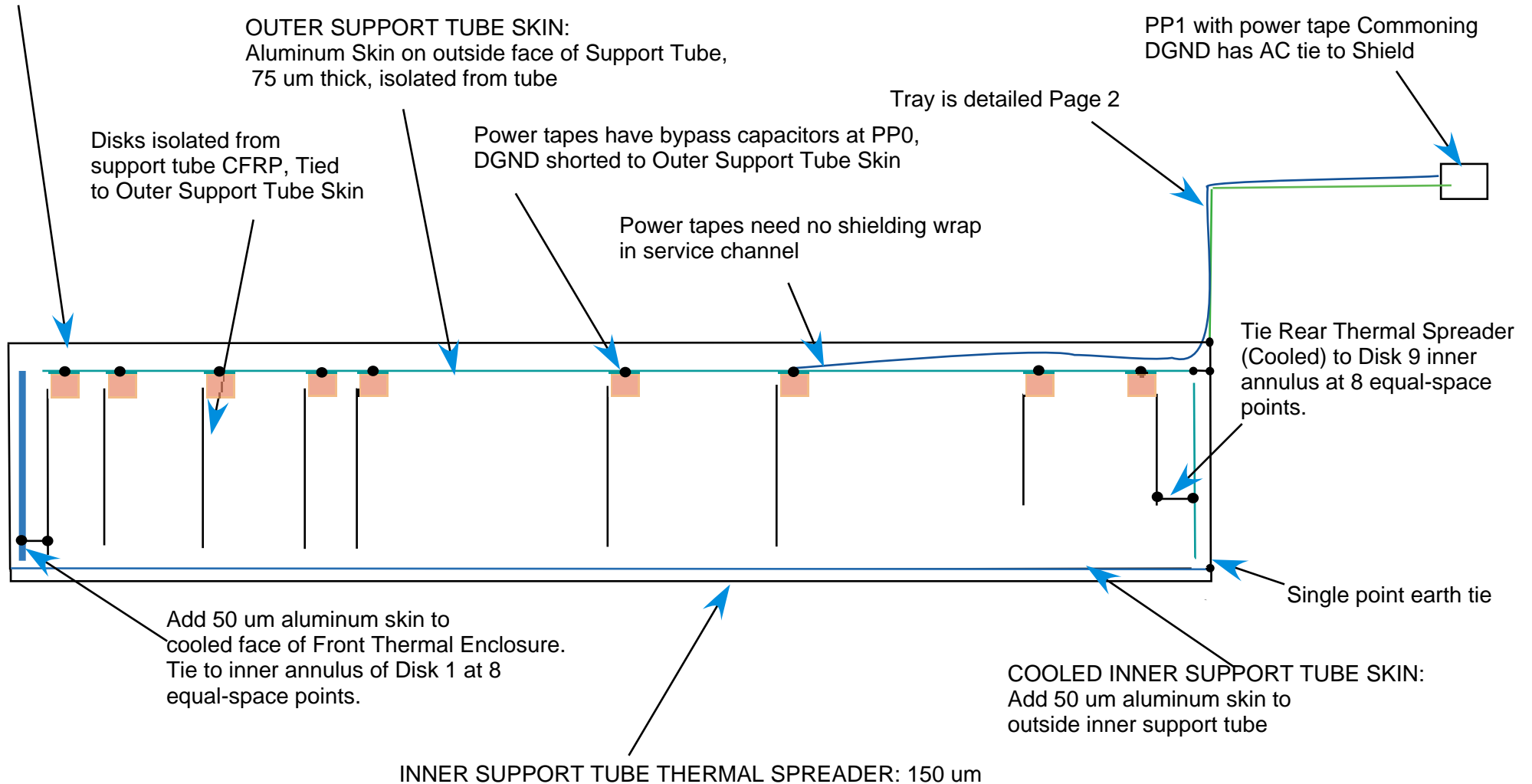
Tie Rear Thermal Spreader
(Cooled) to Disk 9 inner
annulus at 8 equal-space
points.

Add 50 μm aluminum skin to
cooled face of Front Thermal Enclosure.
Tie to inner annulus of Disk 1 at 8
equal-space points.

Single point earth tie

COOLED INNER SUPPORT TUBE SKIN:
Add 50 μm aluminum skin to
outside inner support tube

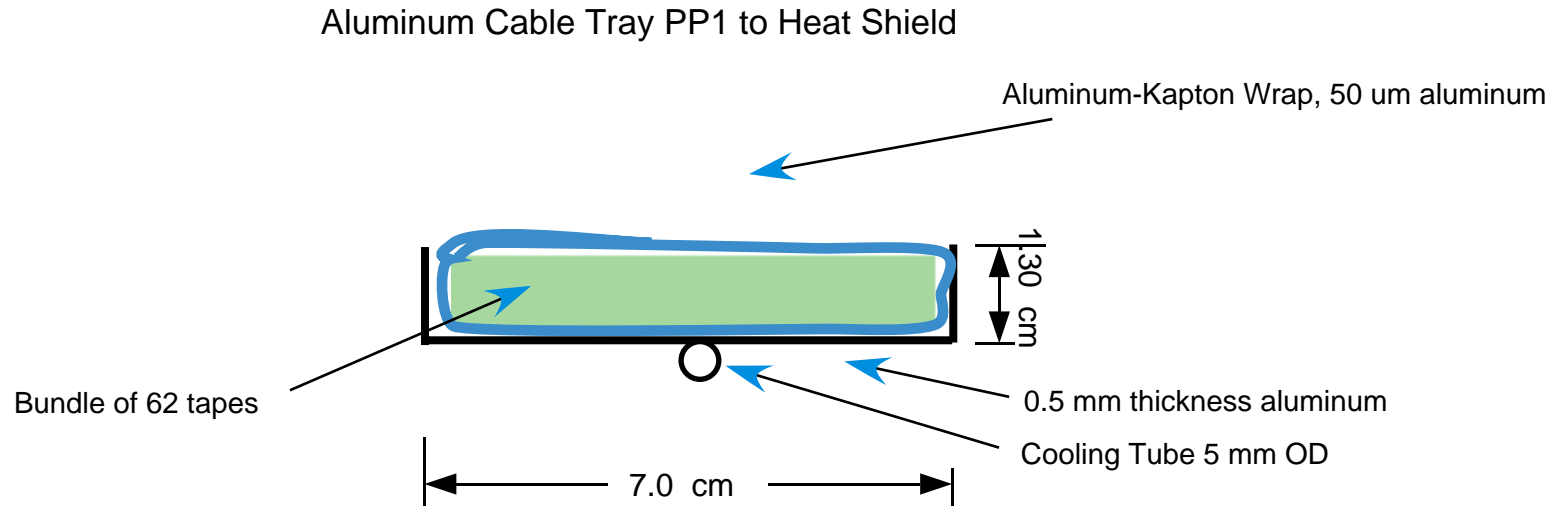
INNER SUPPORT TUBE THERMAL SPREADER: 150 μm



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Tray is isolated from other conductors

Attachment to heat shield uses plated contact areas, mechanically clamped, no epoxy for electrical contact